

ADHESIVE SHEET FOR BACKGRINDING, SEMICONDUCTOR WAFER MANUFACTURING METHOD, AND SUBSTRATE SHEET

ABSTRACT

The present invention aims to provide an adhesive sheet for back grinding capable of enhance followability of a base material layer to a convex part of a semiconductor wafer.

According to the present invention, provided is an adhesive sheet for back grinding of a semiconductor wafer having a convex part, comprising: a base material layer; and an adhesive layer provided on the base material layer, wherein: the adhesive layer comprises an opening part having a diameter smaller than a diameter of the semiconductor wafer; the adhesive layer is adhered to an outer peripheral part of the semiconductor wafer such that the convex part of the semiconductor wafer is placed in the opening part; the adhesive layer is configured so that the convex part is protected by the base material layer with the semiconductor wafer adhered to the adhesive layer; the base material layer comprises a cushion layer and a barrier layer; and an oxygen permeability of the base material layer at 25°C and at RH0% measured base on JIS K 7126-2 (isobaric method) is 1000 ml/(m²·24h·atm) or lower.

[Fig. 1]